

Technology & Industry Alliances

Available Technologies

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Tech ID: 19316

ADDITIONAL TECHNOLOGIES BY THESE INVENTORS

- High-Quality N-Face GaN, InN, AIN by MOCVD
- Defect Reduction in GaN films using in-situ SiNx Nanomask
- A Structure For Increasing Mobility In A High-Electron-Mobility Transistor
- Improved Fabrication of Nonpolar InGaN Thin Films, Heterostructures, and Devices
- Methods for Locally Changing the Electric Field Distribution in Electron Devices
- ▶ Technique for the Nitride Growth of Semipolar Thin Films, Heterostructures, and Semiconductor Devices
- (In,Ga,AI)N Optoelectronic Devices with Thicker Active Layers for Improved Performance
- GaN-based Vertical Metal Oxide Semiconductor and Junction Field Effect Transistors
- Novel Current-Blocking Layer in High-Power Current Aperture Vertical Electron Transistors (CAVETs)
- Iii-N Transistor With Stepped Cap Layers
- III-N Based Material Structures and Circuit Modules Based on Strain Management

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